

MOSFET – Power, Single P-Channel -40 V, 13.8 mΩ, -52.1 A NVMFS014P04M8L

Features

- Small Footprint for Compact Design
- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVMFWS014P04M8L – Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		V _{DSS}	-40	V
Gate-to-Source Voltage		V _{GS}	±20	V
Continuous Drain Current R _{θJC} (Notes 1, 2, 4)	Steady State	T _C = 25°C	I _D	A
		T _C = 100°C	-36.9	
Power Dissipation R _{θJC} (Notes 1, 2)		T _C = 25°C	P _D	W
		T _C = 100°C	60	
Continuous Drain Current R _{θJA} (Notes 1, 3, 4)	Steady State	T _A = 25°C	I _D	A
		T _A = 100°C	-8.8	
Power Dissipation R _{θJA} (Notes 1, 3)		T _A = 25°C	P _D	W
		T _A = 100°C	3.6	
Pulsed Drain Current	T _A = 25°C, t _p = 10 µs	I _{DM}	-268	A
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)		I _S	-50	A
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = -6.1 A)		E _{AS}	133	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

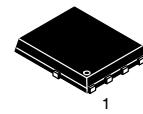
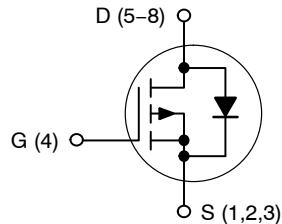
THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

Parameter	Symbol	Value	Unit
Junction-to-Case – Steady State (Drain) (Notes 1, 2, 4)	R _{θJC}	2.5	°C/W
Junction-to-Ambient – Steady State (Note 3)	R _{θJA}	41.5	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. Assumes heat-sink sufficiently large to maintain constant case temperature independent of device power.
3. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
4. Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX
-40 V	13.8 mΩ @ -10 V	-52.1 A
	19.7 mΩ @ -4.5 V	

P-Channel MOSFET



MARKING DIAGRAM
DFN5
(SO-8FL)
CASE 488AA
STYLE 1

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

NVMFS014P04M8L

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0 \text{ V}$, $I_D = -250 \mu\text{A}$	-40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(\text{BR})\text{DSS}/T_J}$			21		$\text{mV}/^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}} = 0 \text{ V}$, $V_{\text{DS}} = -40 \text{ V}$	$T_J = 25^\circ\text{C}$		-1.0	μA
			$T_J = 125^\circ\text{C}$		-1000	
Gate-to-Source Leakage Current	I_{GSS}	$V_{\text{DS}} = 0 \text{ V}$, $V_{\text{GS}} = \pm 20 \text{ V}$			± 100	nA

ON CHARACTERISTICS (Note 5)

Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{GS}} = V_{\text{DS}}$, $I_D = -420 \mu\text{A}$	-1.0		-2.4	V
Negative Threshold Temperature Coefficient	$V_{\text{GS}(\text{TH})/T_J}$			5.1		$\text{mV}/^\circ\text{C}$
Drain-to-Source On Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10 \text{ V}$, $I_D = -15 \text{ A}$		10	13.8	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5 \text{ V}$, $I_D = -7.5 \text{ A}$		14.6	19.7	
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -1.5 \text{ V}$, $I_D = -15 \text{ A}$		42		S

CHARGES AND CAPACITANCES

Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$, $V_{\text{DS}} = -20 \text{ V}$		1734		pF
Output Capacitance	C_{oss}			682		
Reverse Transfer Capacitance	C_{rss}			32		
Total Gate Charge	$Q_{\text{G}(\text{TOT})}$	$V_{\text{DS}} = -20 \text{ V}$, $I_D = -20 \text{ A}$	$V_{\text{GS}} = -4.5 \text{ V}$	12.5		nC
			$V_{\text{GS}} = -10 \text{ V}$	26.5		
Threshold Gate Charge	$Q_{\text{G}(\text{TH})}$	$V_{\text{GS}} = -10 \text{ V}$, $V_{\text{DS}} = -20 \text{ V}$, $I_D = -30 \text{ A}$		2.6		nC
Gate-to-Source Charge	Q_{GS}			5.6		
Gate-to-Drain Charge	Q_{GD}			3.8		
Plateau Voltage	V_{GP}			3.2		V

SWITCHING CHARACTERISTICS, $V_{\text{GS}} = -4.5 \text{ V}$ (Note 6)

Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = -4.5 \text{ V}$, $V_{\text{DS}} = -20 \text{ V}$, $I_D = -30 \text{ A}$, $R_G = 2.5 \Omega$		11.5		ns
Rise Time	t_r			97.4		
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			44.5		
Fall Time	t_f			38.2		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V_{SD}	$V_{\text{GS}} = 0 \text{ V}$, $I_S = -15 \text{ A}$	$T_J = 25^\circ\text{C}$		-0.86	-1.25	V
			$T_J = 125^\circ\text{C}$		-0.74		
Reverse Recovery Time	t_{RR}	$V_{\text{GS}} = 0 \text{ V}$, $dI_S/dt = 100 \text{ A}/\mu\text{s}$, $I_S = -10 \text{ A}$			34.9		ns
Charge Time	t_a				15.8		
Discharge Time	t_b				19.1		
Reverse Recovery Charge	Q_{RR}				16.3	52	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2\%$.

6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

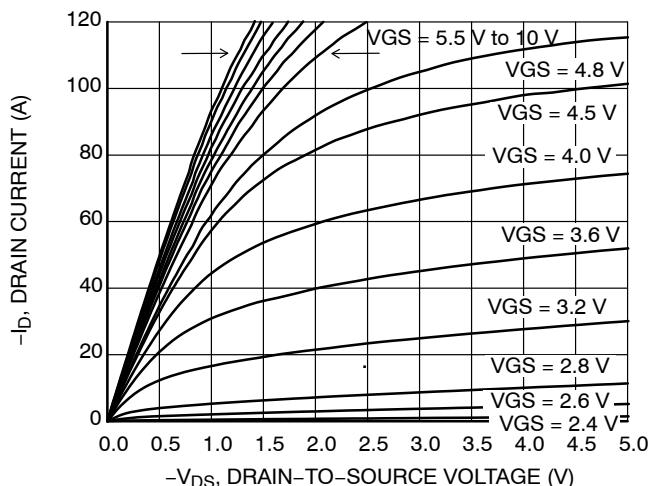


Figure 1. On-Region Characteristics

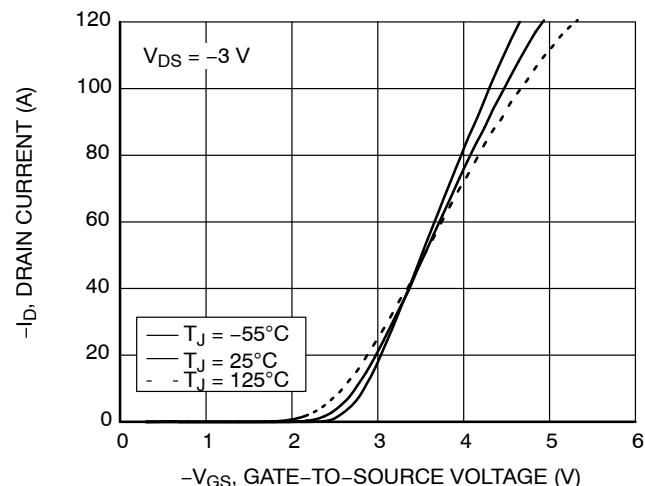


Figure 2. Transfer Characteristics

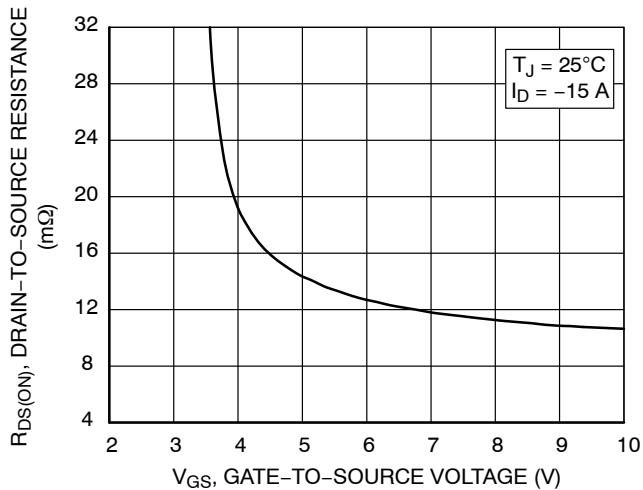


Figure 3. On-Resistance vs. Gate-to-Source Voltage

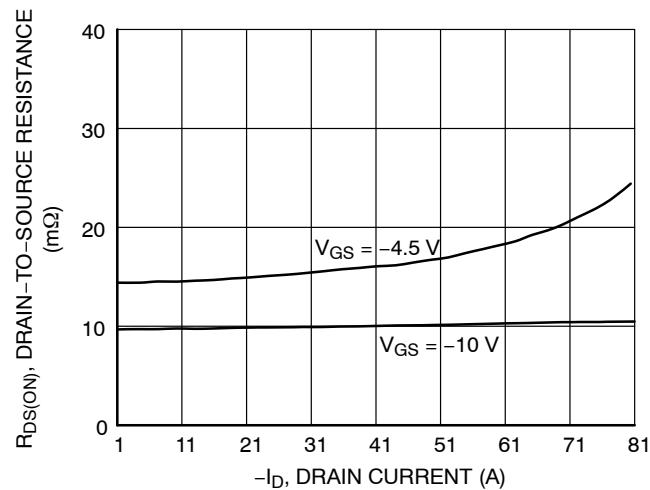


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

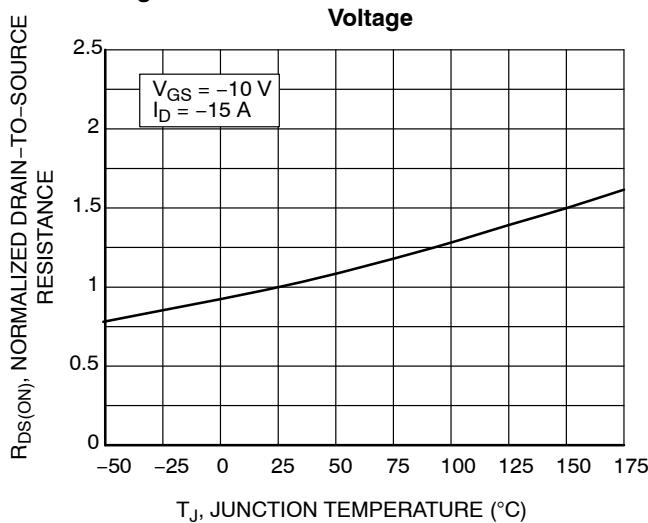


Figure 5. On-Resistance Variation with Temperature

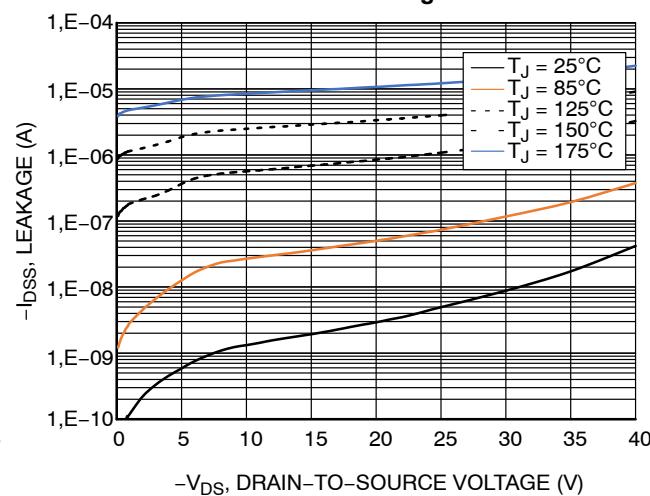


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS (continued)

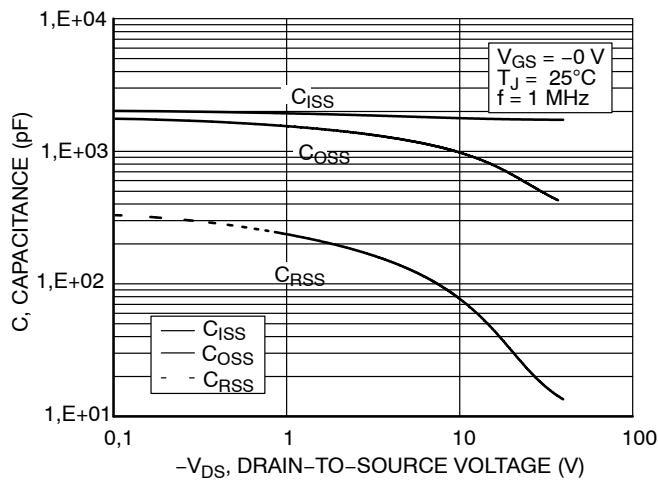


Figure 7. Capacitance Variation

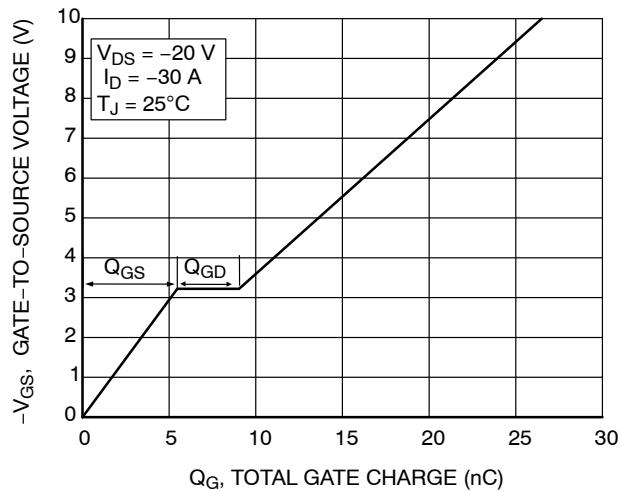


Figure 8. Gate-to-Source vs. Total Charge

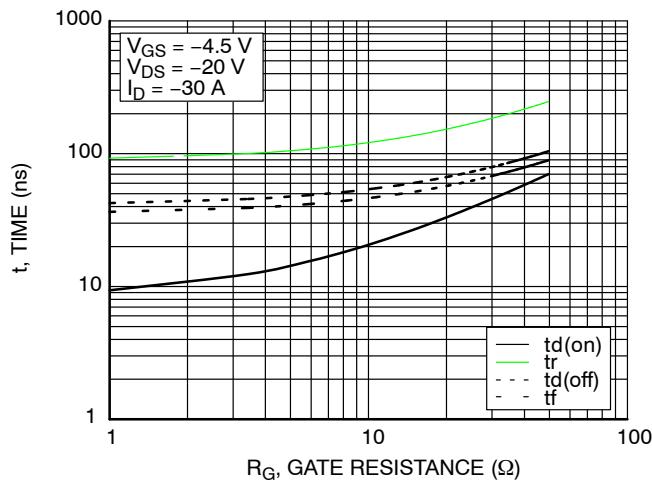


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

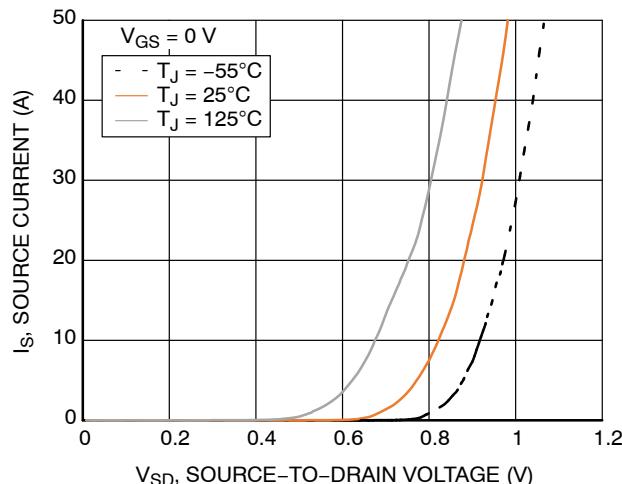


Figure 10. Diode Forward Voltage vs. Current

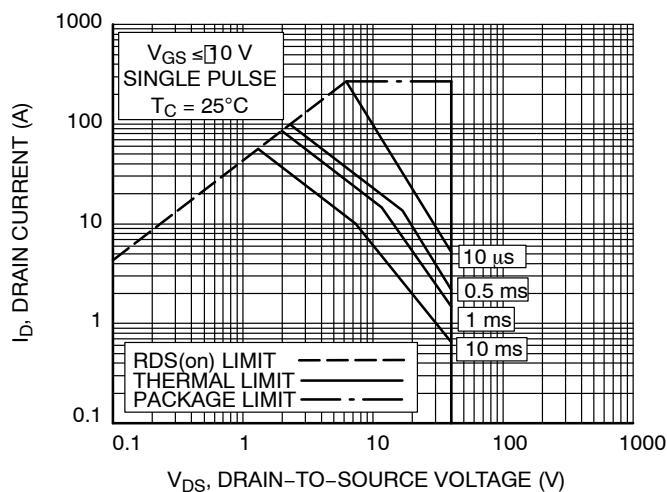


Figure 11. Maximum Rated Forward Biased Safe Operating Area

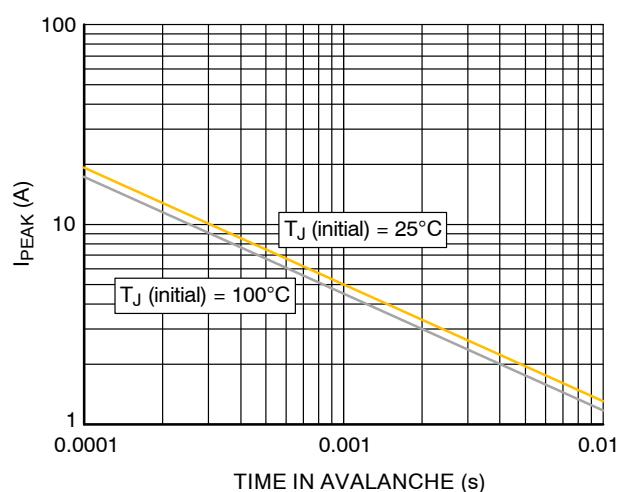


Figure 12. Maximum Drain Current vs. Time in Avalanche

TYPICAL CHARACTERISTICS (continued)

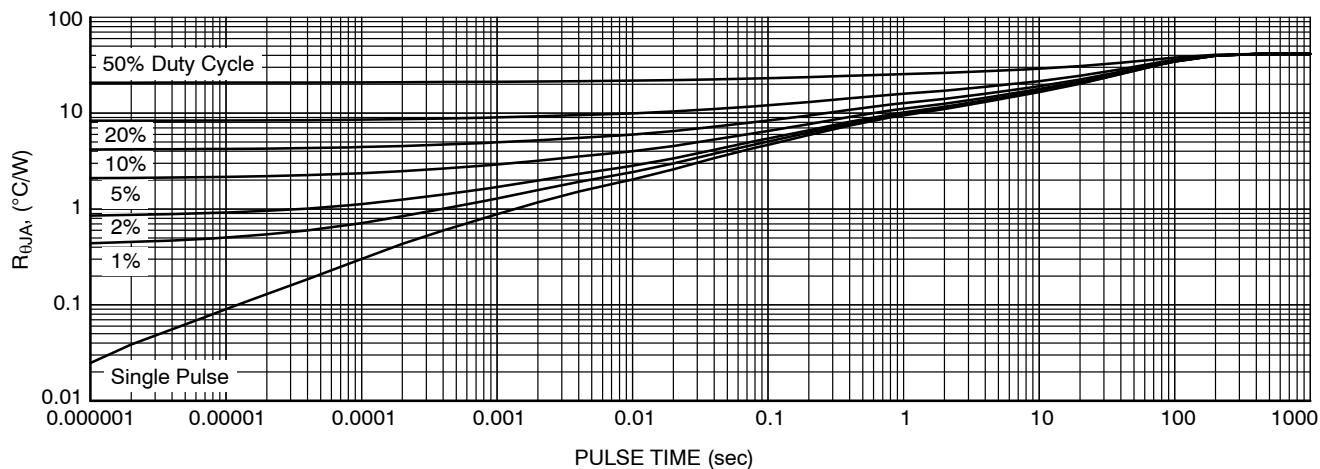
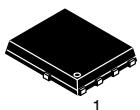


Figure 13. Thermal Response

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVMFS014P04M8LT1G	014P04	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFWS014P04M8LT1G	014P4W	DFN5 (Pb-Free, Wettable Flank)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



SCALE 2:1

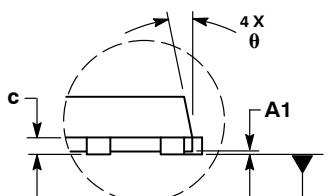
DFN5 5x6, 1.27P
(SO-8FL)
CASE 488AA
ISSUE N

DATE 25 JUN 2018

NOTES:

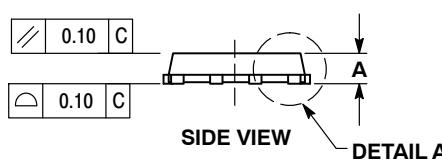
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	----	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D	5.00	5.15	5.30
D1	4.70	4.90	5.10
D2	3.80	4.00	4.20
E	6.00	6.15	6.30
E1	5.70	5.90	6.10
E2	3.45	3.65	3.85
e	1.27 BSC		
G	0.51	0.575	0.71
K	1.20	1.35	1.50
L	0.51	0.575	0.71
L1	0.125 REF		
M	3.00	3.40	3.80
θ	0 °	----	12 °

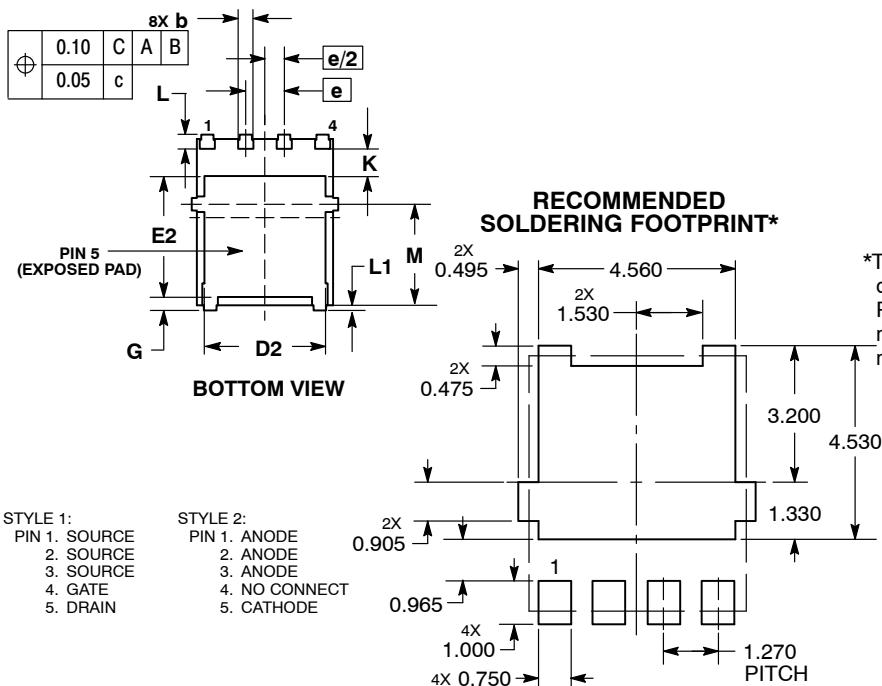


DETAIL A

SEATING PLANE



DETAIL A



STYLE 1:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN

STYLE 2:
PIN 1. ANODE
2. ANODE
3. ANODE
4. NO CONNECT
5. CATHODE

DIMENSIONS: MILLIMETERS

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN5 5x6, 1.27P (SO-8FL)	PAGE 1 OF 1

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